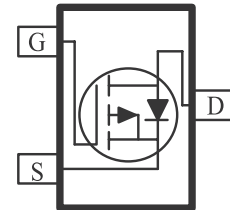
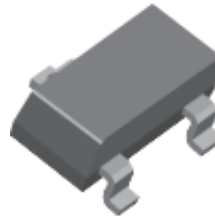


P - Channel Logic Level MOSFET

These miniature surface mount MOSFETs utilize High Cell Density process. Low $r_{DS(on)}$ assures minimal power loss and conserves energy, making this device ideal for use in power management circuitry. Typical applications are lower voltage application, power management in portable and battery-powered products such as computers, printers, PCMCIA cards, cellular and cordless telephones.

- Low $r_{DS(on)}$ Provides Higher Efficiency and Extends Battery Life
- Fast Switch
- Low Gate Charge
- Miniature SOT-23 Surface Mount Package Saves Board Space



PRODUCT SUMMARY		
V_{DS} (V)	$r_{DS(on)}$ (Ω)	I_D (A)
-30	0.30 @ $V_{GS} = -10$ V	-1.0
	0.50 @ $V_{GS} = -4.5$ V	-0.9

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ UNLESS OTHERWISE NOTED)				
Parameter		Symbol	Maximum	Units
Drain-Source Voltage		V_{DS}	30	V
Gate-Source Voltage		V_{GS}	± 20	
Continuous Drain Current ^a	$T_A = 25^\circ\text{C}$	I_D	± 0.9	A
	$T_A = 70^\circ\text{C}$		± 0.75	
Pulsed Drain Current ^b		I_{DM}	± 10	
Continuous Source Current (Diode Conduction) ^a		I_S	0.4	A
Power Dissipation ^a	$T_A = 25^\circ\text{C}$	P_D	0.5	W
	$T_A = 70^\circ\text{C}$		0.42	
Operating Junction and Storage Temperature Range		T_J, T_{stg}	-55 to 150	$^\circ\text{C}$

THERMAL RESISTANCE RATINGS				
Parameter		Symbol	Maximum	Units
Maximum Junction-to-Ambient ^a	$t \leq 5$ sec	R_{THJA}	250	$^\circ\text{C/W}$
	Steady-State		285	

Notes

- Surface Mounted on 1" x 1" FR4 Board.
- Pulse width limited by maximum junction temperature

SPECIFICATIONS (T _A = 25°C UNLESS OTHERWISE NOTED)						
Parameter	Symbol	Test Conditions	Limits			Unit
			Min	Typ	Max	
Switch Off Characteristics						
Drain-Source Breakdown Voltage	V _(BR) DSS	V _{GS} = 0 V, I _D = -250 uA	-30			
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = -24 V, V _{GS} = 0 V			-1	μA
		V _{DS} = -24 V, V _{GS} = 0 V, T _J = 55°C			-10	
Gate-Body Leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ±20 V			±100	nA
Switch On Characteristics						
Gate-Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = -250 uA	-0.80	-1.7	-2.6	V
On-State Drain Current ^A	I _{D(on)}	V _{DS} = -5 V, V _{GS} = -4.5 V	-2			A
Drain-Source On-Resistance ^A	r _{DS(on)}	V _{GS} = -10 V, I _D = -1.0 A		0.25	0.30	Ω
		V _{GS} = -4.5 V, I _D = -0.9 A T _J = 55°C		0.53	0.66	
		V _{GS} = -4.5 V, I _D = -0.9 A		0.45	0.50	
Forward Tranconductance ^A	g _{fs}	V _{DS} = -5 V, I _D = -1.1 A		2		S
Diode Forward Voltage	V _{SD}	I _S = -0.4 A, V _{GS} = 0 V		-0.70	-1.2	V
Dynamic ^b						
Total Gate Charge	Q _g	V _{DS} = -10 V, V _{GS} = -5 V, I _D = -0.9 A		2.0	3.0	nC
Gate-Source Charge	Q _{gs}			0.5		
Gate-Drain Charge	Q _{gd}			1.1		
Switching						
Turn-On Delay Time	t _{d(on)}	V _{DS} = -10 V, I _D = -0.9 A, R _G = 50 Ω, V _{GEN} = -10 V		8	16	ns
Rise Time	t _r			16	32	
Turn-Off Delay Time	t _{d(off)}			36	93	
Fall-Time	t _f			33	94	

Notes

- Pulse test: $PW \leq 300\mu\text{s}$ duty cycle $\leq 2\%$.
- Guaranteed by design, not subject to production testing.

Typical Electrical Characteristics

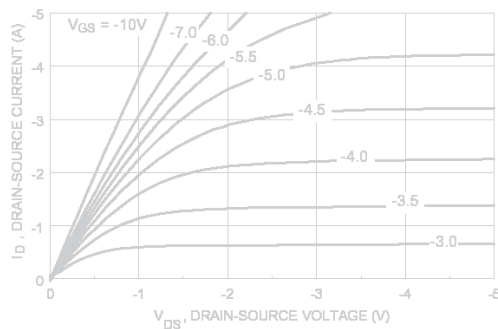


Figure 1. On-Region Characteristics

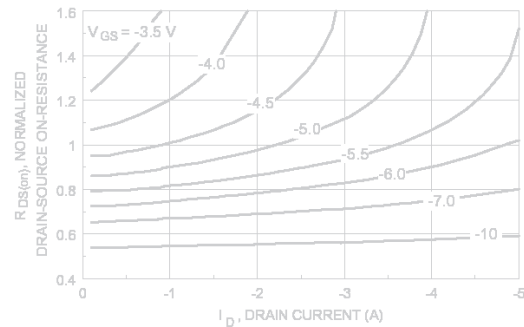


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage

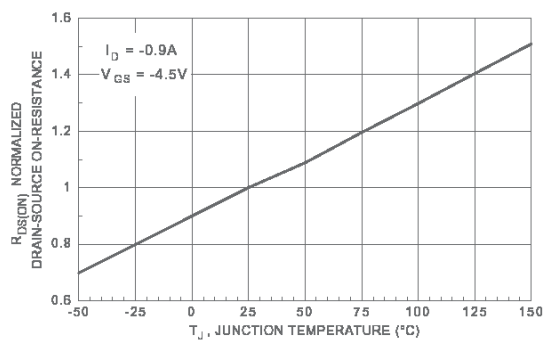


Figure 3. On-Resistance Variation with Temperature

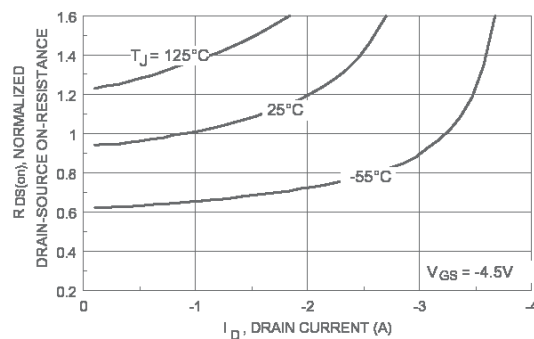


Figure 4. On-Resistance Variation with Gate to Source Voltage

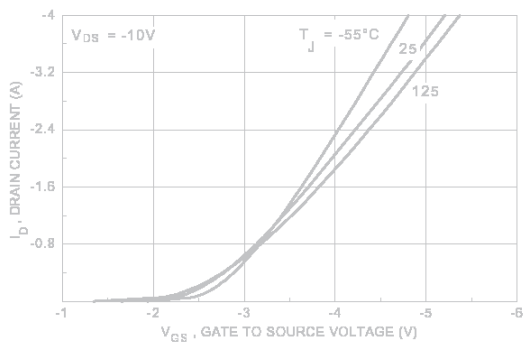


Figure 5. Transfer Characteristics

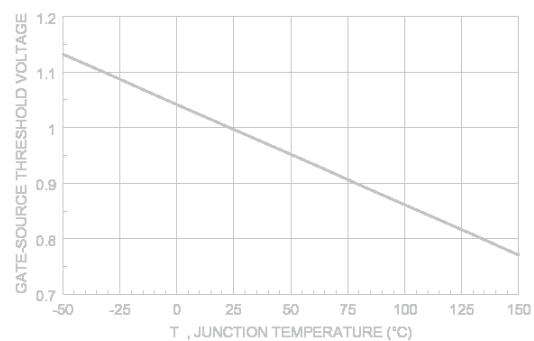


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature

Typical Electrical Characteristics

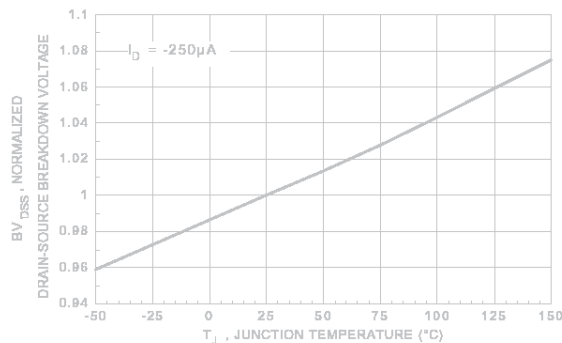


Figure 7. Breakdown Voltage With Temperature

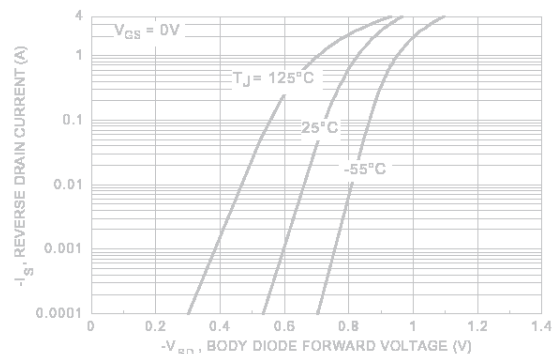


Figure 8. Body Diode Forward Voltage With Source Current & Temperature

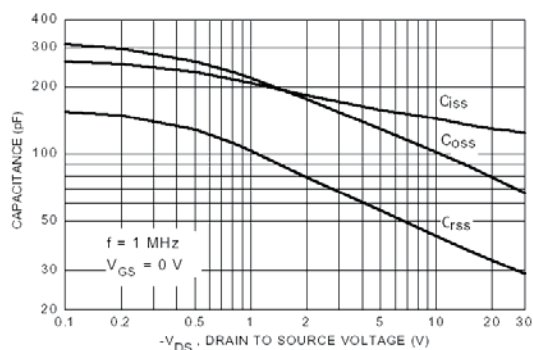


Figure 9. Capacitance Characteristic

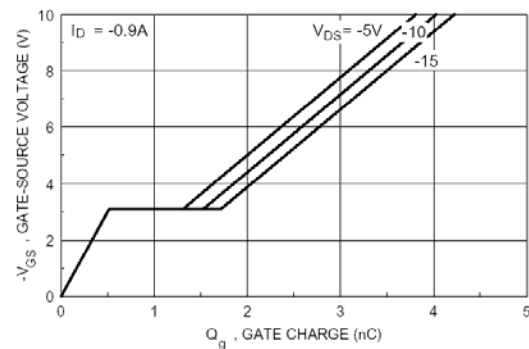


Figure 10. Gate Charge Characteristic

Normalized Thermal Transient Impedance, Junction to Ambient

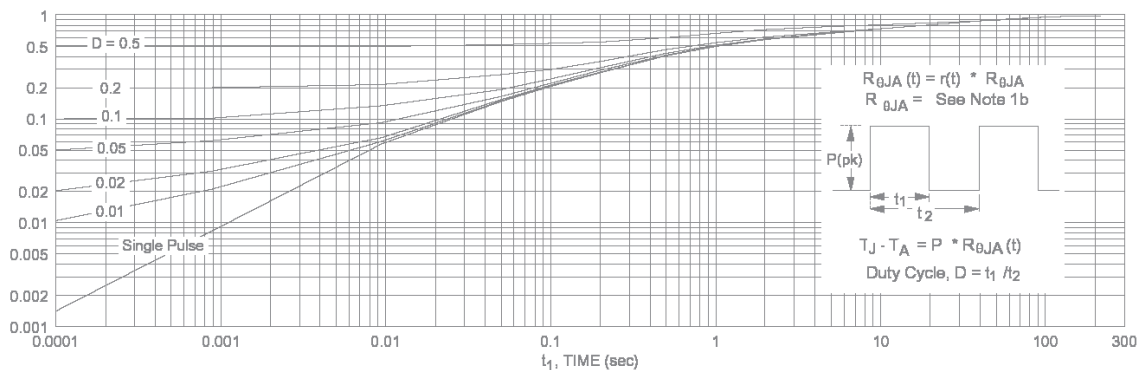


Figure 11. Transient Thermal Response Curve

Typical Electrical Characteristics

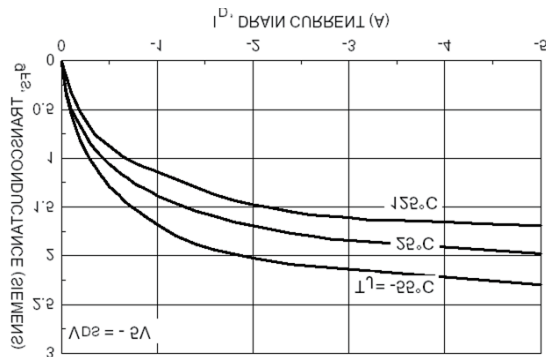


Figure 13. Transconductance Variation With Current & Temperature

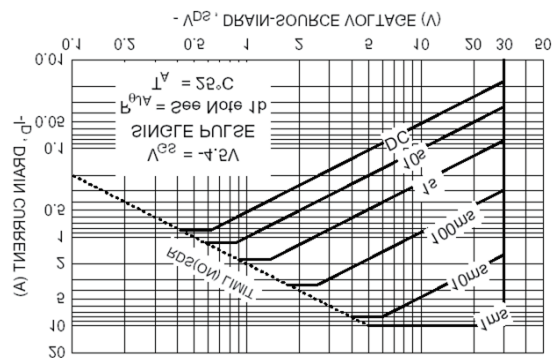


Figure 14. Maximum Safe Operation Area

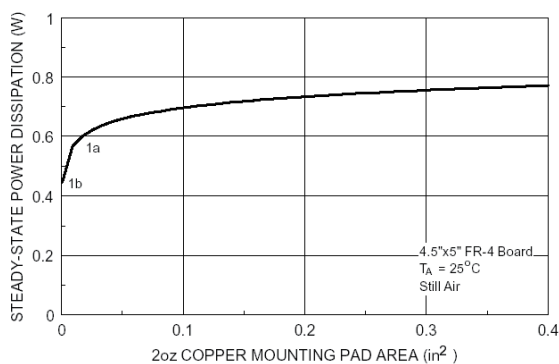


Figure 15. SOT-3 Maximum Steady-State Variation Power Dissipation versus Copper Pad Area

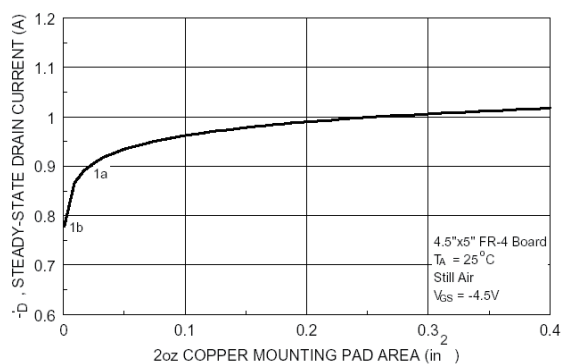
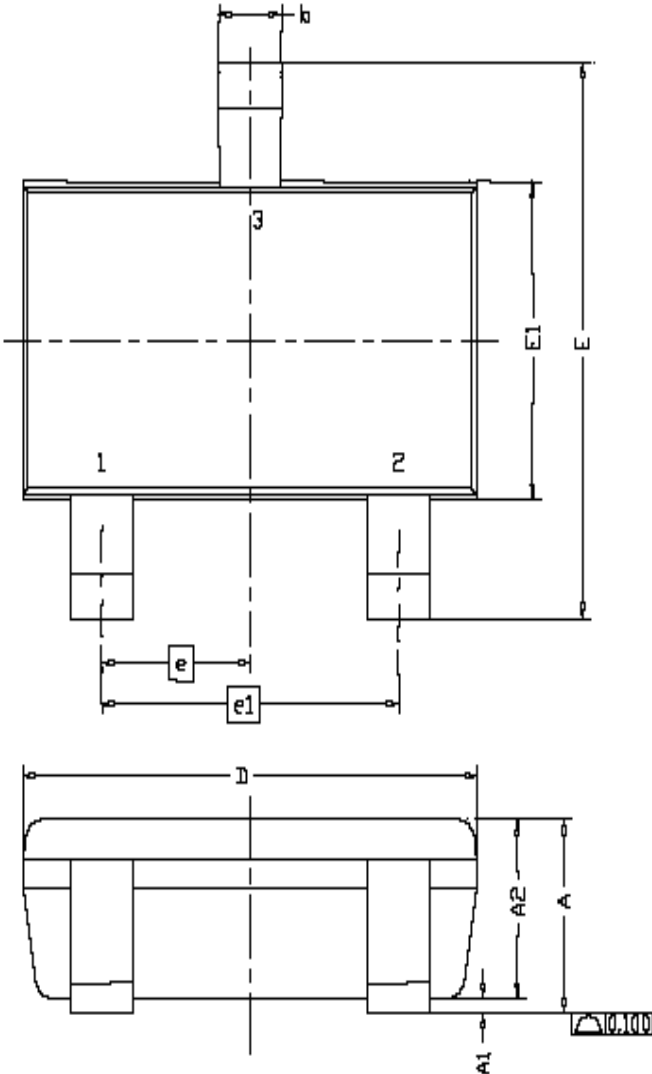


Figure 16. Maximum State-State Drain Current Current Versus Copper Pad Area

Package Information



DIM.	MILLIMETERS		
	MIN	NOM	MAX
A	0.935	0.95	1.10
A1	0.01	---	0.10
A2	0.85	0.90	0.925
b	0.30	0.40	0.50
c	0.10	0.15	0.25
D	2.70	2.90	3.10
E	2.60	2.80	3.00
E1	1.40	1.60	1.80
e	0.95 BSC		
e1	1.90 BSC		
L	0.30	0.40	0.60
L1	0.60REF		
L2	0.25BSC		
R	0.10	---	---
θ	0°	4°	8°
θ1	7°NOM		

